

CLAIMS

1. A hot melt adhesive that can be applied to a substrate at a temperature of less than about 110°C, said adhesive comprising an ethylene copolymer, a paraffin wax, a rosin derived tackifier and an aromatic tackifier.
2. The adhesive of claim 1 that can be applied to a substrate at a temperature of from about 80°C to a temperature of about 100°C.
3. The adhesive of claim 2 that can be applied to a substrate at a temperature of from about 80°C to a temperature of about 90°C.
4. The adhesive of claim 1 wherein the adhesive polymer is ethylene n-butyl acrylate.
5. The adhesive of claim 4 comprising from about 20 to about 40 wt % of said ethylene n-butyl acrylate, from about 20 to about 40 wt % of said wax, from about 5 to about 30 wt % of an aromatic tackifier, and from about 2 to about 40 wt % a rosin tackifier .
6. An article of manufacture comprising the adhesive of claim 1.
7. The article of claim 6 which is a carton or carton, case, tray or bag.
8. A method of sealing and/or forming a case, carton, tray or bag comprising applying the hot melt adhesive of claim 1 to seal and/or form the case, carton, tray, or bag.
9. A packaged article contained within a carton, case, tray or bag, wherein the carton, case, tray or bag comprises the adhesive of claim 1.

10. The packaged article of claim 9 which is stored at temperature below about 0 °C
11. The packaged article of claim 12 which is a packaged food article.
12. A process for bonding a substrate to a similar or dissimilar substrate comprising applying to at least one substrate a molten hot melt adhesive composition and bonding said substrate together, said hot melt adhesive comprising the adhesive of claim 1, wherein the adhesive is applied at a temperature of less than about 100 °C
13. The process of claim 12 wherein the adhesive is applied at a temperature of about 80°C to about 90°C.